Special Topics on Basic EECS I Design Technology Co-Optimization

Lecture 1

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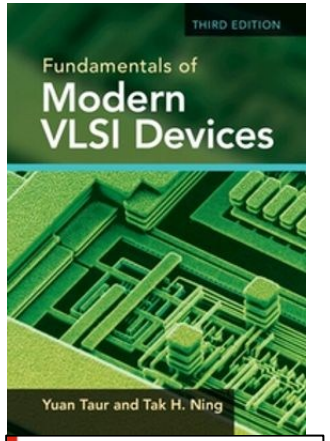
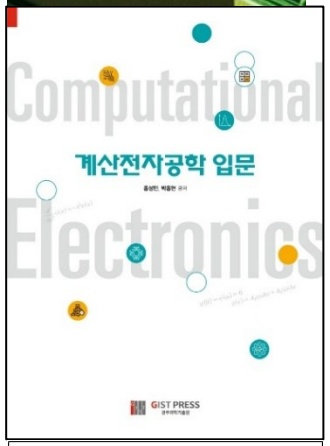
Outline

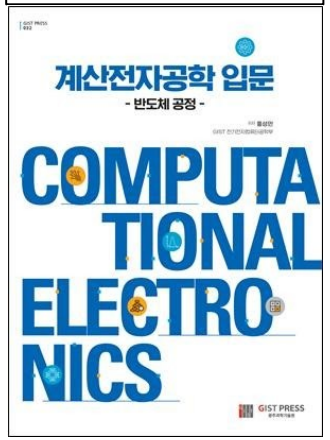
- Design Technology Co-Optimization (DTCO)
  - A framework aimed at achieving continued scaling and performance improvements in advanced semiconductor technologies
- Purpose
  - Course dedicated to DTCO is rarely found.
  - Initial exposure to DCTO
- Contents
  - Basic tools for layout, process emulation, device simulation, and circuit simulation
  - Several (TCAD-based) DTCO examples

Prerequisite and refrences

- Recommended courses
  - Electronic Circuit (EC3207)
  - Semiconductor Materials and Devices (EC3206)
  - VLSI Devices (EC4313)
- No textbook
  - Lecture materials will be distributed.
- References
  - Fundamentals of Modern VLSI Devices by Taur & Ning
  - 계산전자공학 입문 by Hong & Park
  - 계산전자공학 입문 – 반도체 공정 by Hong







Resources

- Presentation materials
  https://github.com/hi2ska2/dtco2025f

- Homework submission and notice
  - GIST LMS system

- YouTube channel
  https://www.youtube.com/@TCADHong

Grading and policy

- Attendance: 10 %
- Homework: 30 %
  - For some of them, you must submit recorded videos. (New in this semester)
- No paper examination
- Final project presentation: 60 %
  - You must submit a recorded video.
  - The submitted video will be posted on my YouTube channel.
- The offline lectures will be live-streamed.

Recorded lectures

- Week 2 (Sep. 8 and Sep. 10)
  - Business trip to Munich (ESSERC)
  - Lecture 3: Recorded video, available at 09:00 on Sep. 8 (on my YouTube channel)
  - Lecture 4: Recorded video, available at 09:00 on Sep. 10 (on my YouTube channel)
  - Attendance: Homework reports
- Additionally, Week 15 (Dec. 8 and Dec. 10)
  - Business trip to San Francisco (IEDM)

L1

As of 2025,

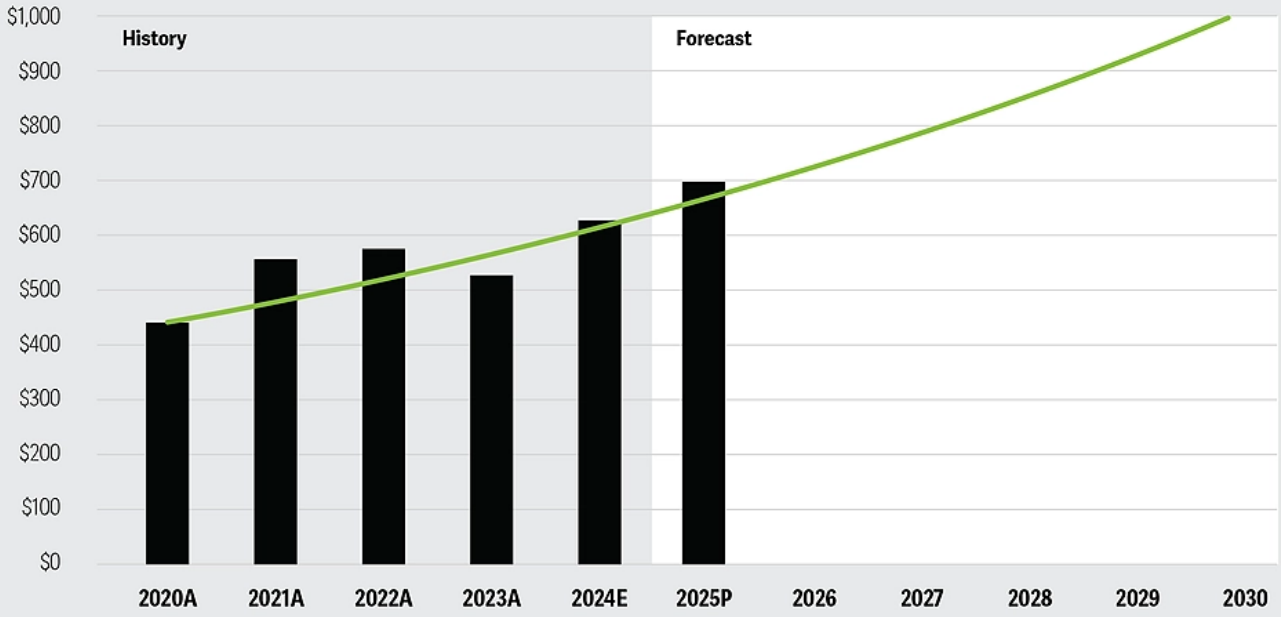
- Growth of semiconductor industry is driven by generative AI chips.
  - CPUs
  - GPUs
  - Data center communications chips
  - Memory
  - Power chips

2025 global semiconductor industry outlook (Deloitte)

Figure 1

Revenues indicate the possibility of the chip industry hitting US$1 trillion in 2030

The path to $1 trillion in semiconductor revenues ($Billions)

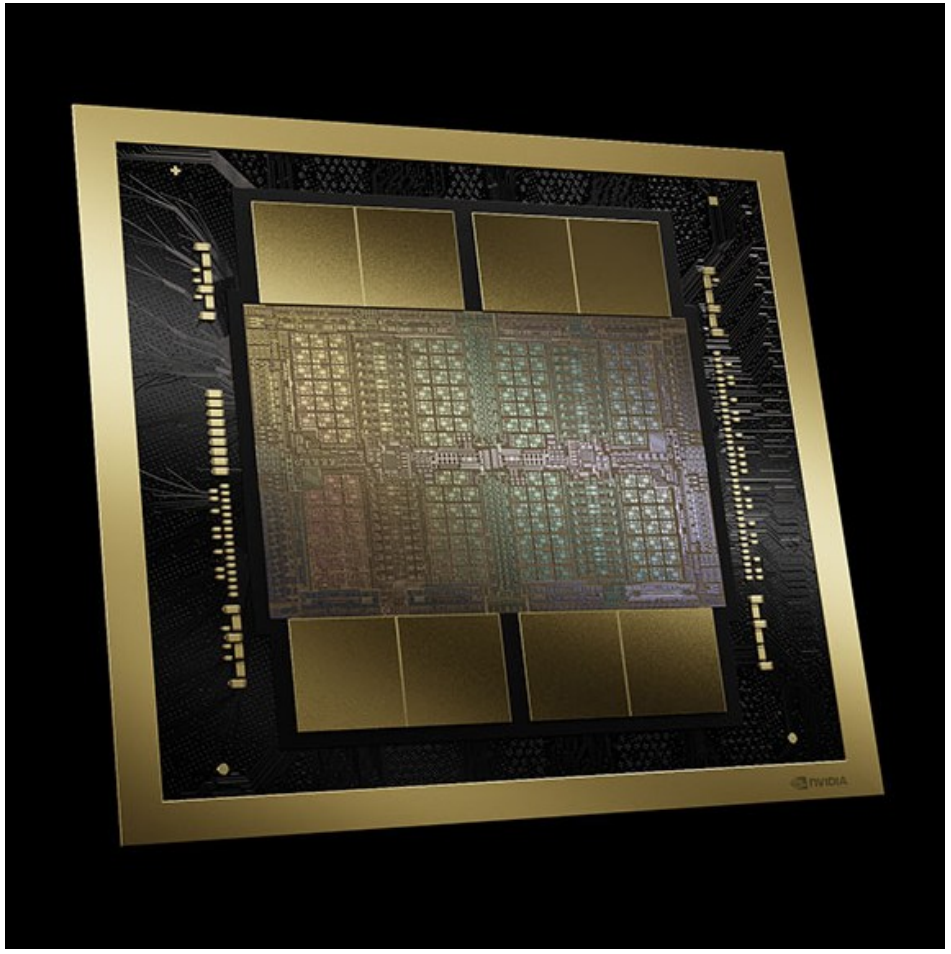


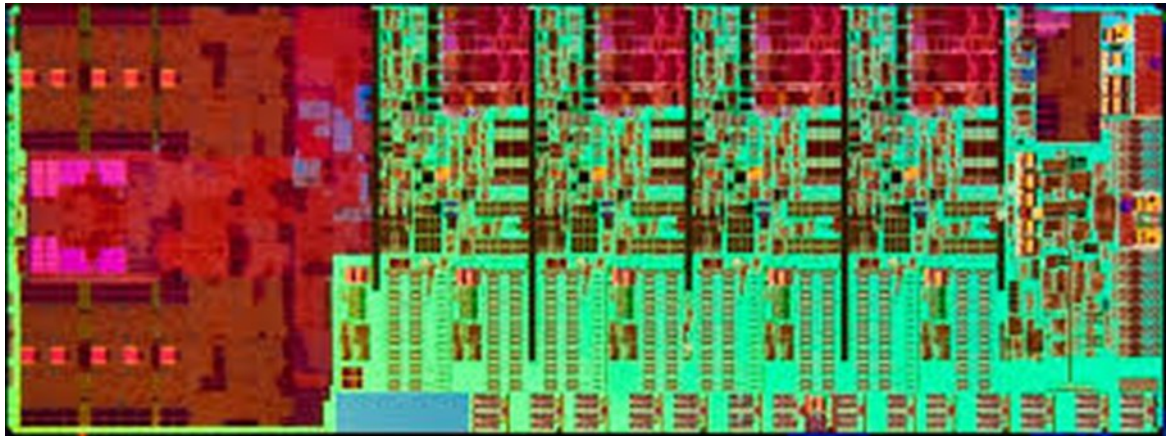
Note: A = Actual, E = Estimate, P = Prediction.
Source: Deloitte analysis and extrapolation based on data from World Semiconductor Trade Statistics.

Deloitte. | deloitte.com/us/en/insights/research-centers/center-for-technology-media-telecommunications.html

Nvidia B200

- A building block of DGX B200 or GB200 NVL72
  - 208 billion transistors





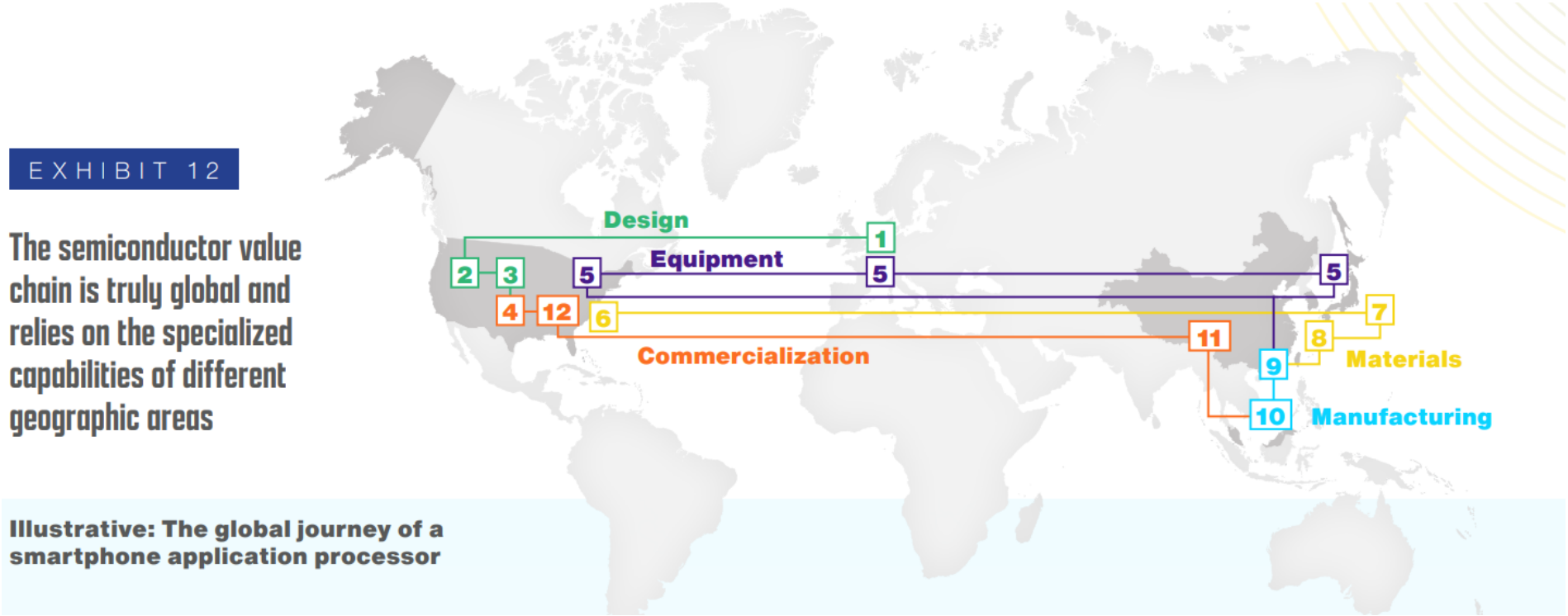
Intel Core i74770K, 2013, 1.4B transistors (Intel)

Nvidia B200, 2024, 208B transistors (Nvidia)

Geopolitical dimensions

- The semiconductor industry is not just economically important.
  - Six major regions (US, South Korea, Japan, mainland China, Taiwan, and Europe)

(Semiconductor Industry Association)



What is the key factor?

- If you run a restaurant, you must orchestrate:
  - Ingredients & suppliers
  - Recipes & standards
  - Chef & brigade
  - Kitchen & equipment
  - Execution on the pass
  - Consistency control
  - Plating & presentation
  - Service & guest experience
  - Ambient & reputation
  - Cost & throughput
  - …

(ChatGPT)

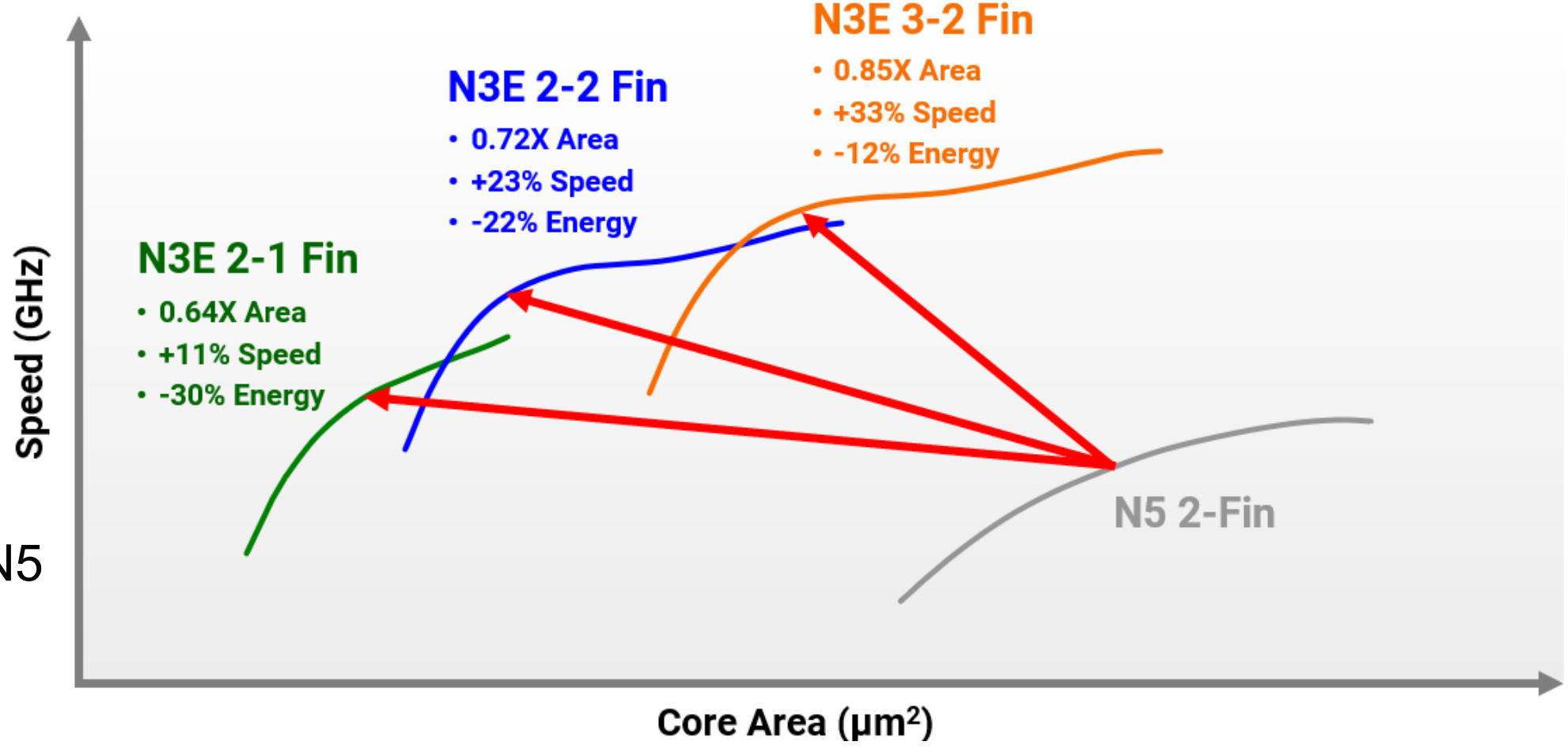
Ultimately, the key is *taste*.

- If the food is not great, nothing else makes up for it.
  - That is the core value.
- What is the equivalent of “taste” in semiconductor manufacturing?
  - Especially for AI chips, expectations are closer to fine dining than fast food.

(Michelin guide)

Power, performance, area (PPA)

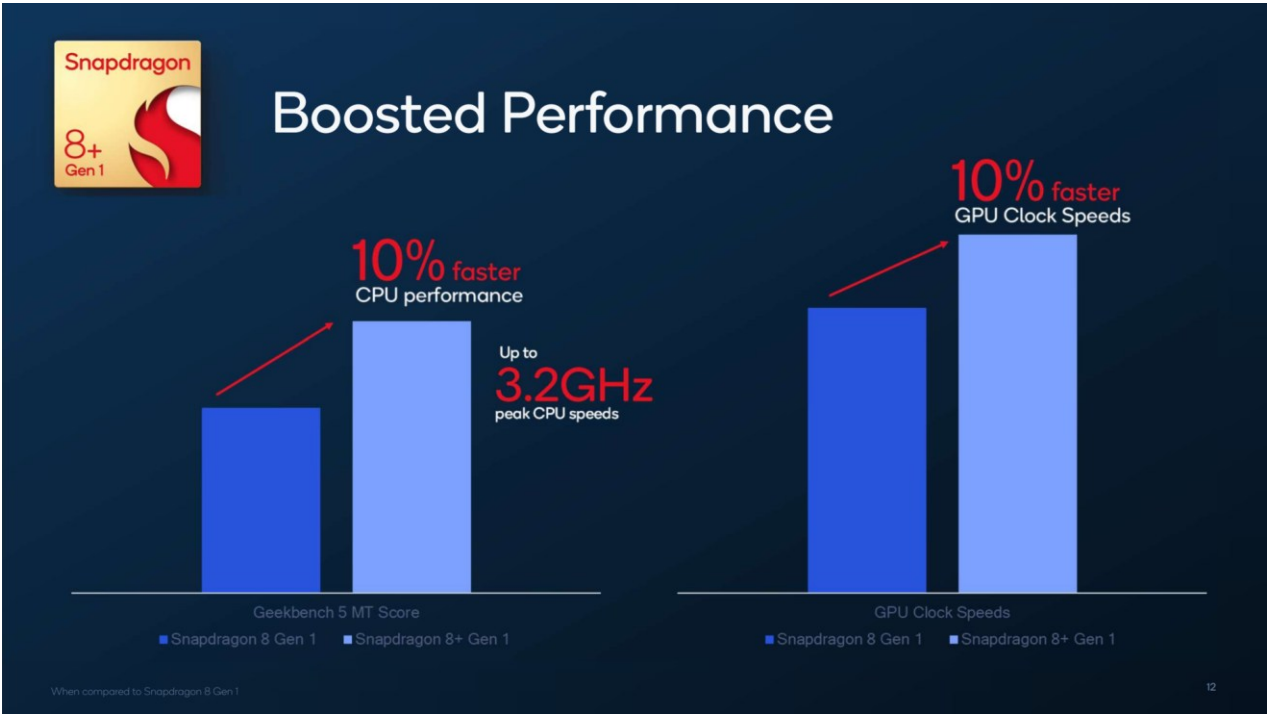
- Low-power (mobile), high performance (high clock speed), and smaller area (more transistors)

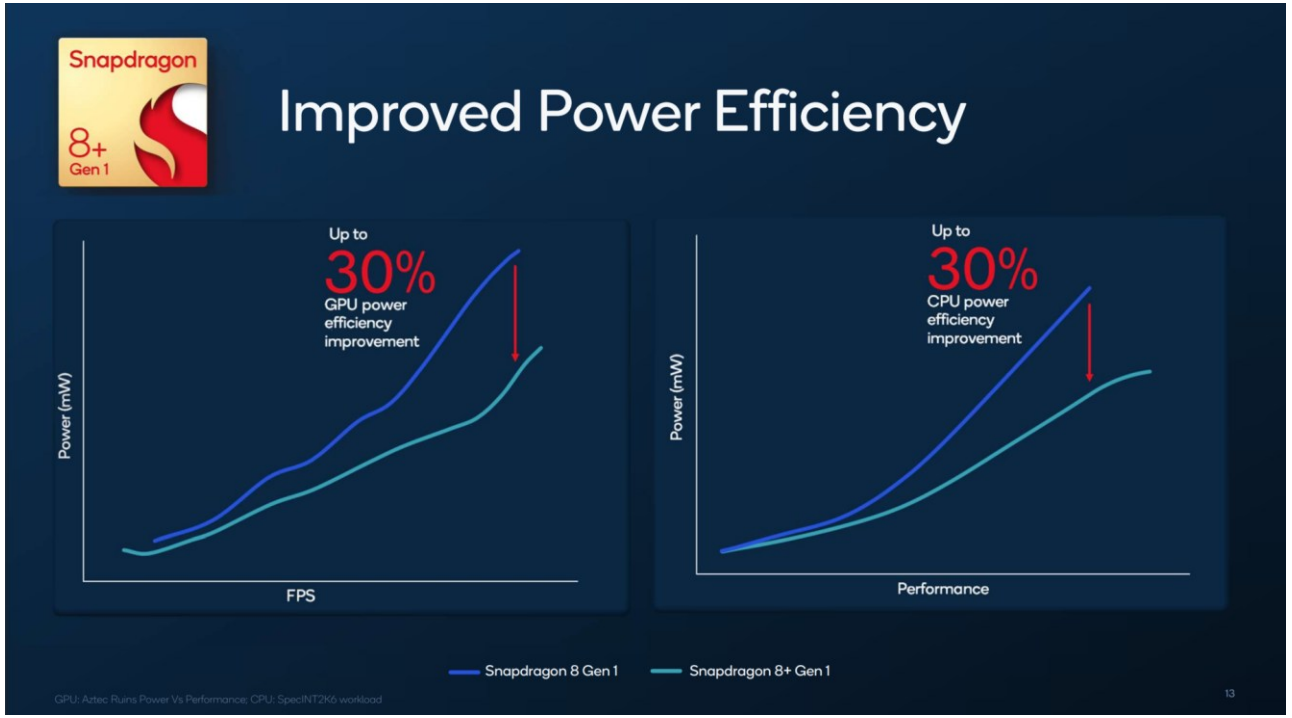


N3 versus N5 (TSMC)

Snapdragon 8 Gen 1 / 8+ Gen 1

- Same architecture, different foundry (Samsung 4LPE / TSMC N4)
  - Foundry choice changes PPA. (20 % area reduction)





+10 % clock (Qualcomm)

+30 % power efficiency (Qualcomm)

Homework#1

- Due: 08:00 on Sep. 3 (Morning in this Wednesday)
- Submit a recorded video. Send it to me via e-mail.
  - Explain the operation of MOSFETs.
  - The video length and scope are up to you.
  - Do not disclose your personal information except for your name.

Thank you!